

# TN3512L, TN4012L

## N-Channel Enhancement-Mode MOS Transistors

T-35-25

**PRODUCT SUMMARY**

PART NUMBER	V <sub>(BR)DSS</sub> (V)	r <sub>DSON</sub> (Ω)	I <sub>D</sub> (A)
TN3512L	350	12	0.16
TN4012L	400	12	0.16

Performance Curves: VNDV40

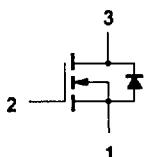
TO-92 (TO-226AA)



BOTTOM VIEW



1 SOURCE  
2 GATE  
3 DRAIN

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS		UNITS
			TN3512L	TN4012L	
Drain-Source Voltage		V <sub>DS</sub>	350	400	V
Gate-Source Voltage		V <sub>GS</sub>	±20	±20	
Continuous Drain Current	T <sub>A</sub> = 25°C	I <sub>D</sub>	±0.16	±0.16	A
	T <sub>A</sub> = 100°C		±0.10	±0.10	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	±0.65	±0.65	
Maximum Power Dissipation	T <sub>A</sub> = 25°C	P <sub>D</sub>	0.80	0.80	W
	T <sub>A</sub> = 100°C		0.32	0.32	
Operating Junction & Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C
Lead Temperature (1/16" from case for 10 sec.)		T <sub>L</sub>	300		

6

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	LIMITS	UNITS
Junction-to-Ambient	R <sub>thJA</sub>	156	K/W

<sup>1</sup>Pulse width limited by maximum junction temperature.

**TN3512L, TN4012L**
 **Siliconix**  
incorporated

SPECIFICATIONS <sup>a</sup>			LIMITS			
PARAMETER	SYMBOL	TEST CONDITIONS	TYP <sup>b</sup>	MIN	MAX	UNIT
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V	TN4012L	420	400	V
		I <sub>D</sub> = 10 μA	TN3512L	400	350	
Gate Threshold Voltage	V <sub>Gsth</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1 mA	1.3	0.6	1.8	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V	±1		±10	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 0.8 x rated V <sub>(BR)DSS</sub> , V <sub>GS</sub> = 0 V			1	μA
		T <sub>J</sub> = 125°C			100	
On-State Drain Current <sup>c</sup>	I <sub>D(ON)</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 4.5 V	300	150		mA
Drain-Source On-Resistance <sup>c</sup>	r <sub>DS(ON)</sub>	V <sub>GS</sub> = 3.5 V, I <sub>D</sub> = 50 mA	10		15	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 150 mA	9		12	
		T <sub>J</sub> = 125°C	17		30	
Forward Transconductance <sup>c</sup>	g <sub>Fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 100 mA	350	125		ms
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 15 V, f = 1 MHz	90		110	pF
Output Capacitance	C <sub>oss</sub>		20		30	
Reverse Transfer Capacitance	C <sub>rss</sub>		5		10	
<b>SWITCHING</b>						
Turn-On Time	t <sub>ON</sub>	V <sub>DD</sub> = 25 V, R <sub>L</sub> = 250 Ω, I <sub>D</sub> = 0.1 A V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 25 Ω	5.5		15	ns
Turn-Off Time	t <sub>OFF</sub>		(Switching time is essentially independent of operating temperature)	40		

## NOTES:

- a. T<sub>A</sub> = 25°C unless otherwise noted.
- b. For design aid only, not subject to production testing.
- c. Pulse test: Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.